

AMENDMENTS TO THE SPECIFICATION

Please replace on page 3, paragraph [16] of the specification, with the following rewritten paragraph as follows.

--[16] Fig. 4 is a section view of a conventional two-layer metal RF module, and Figs. 5 and 6 are section views of the module of Fig. 4 as modified in accordance with another embodiment of the invention. In Fig. 4 a printed circuit board having a core material 40 has conductive metal layers on opposing surfaces including a backside ground plane 41 and an input/output (I/O) contact 42 on the backside and with the topside metal being selectively etched to form contacts 44 and 46 on which a surface mount **[transistor]** capacitor 48 is mounted, metal layer 50 on which an IC die 52 is mounted, a trace layer 54 which forms a microstrip with ground plane 41, and another contact 56. An output capacitor 58 is mounted at one end of trace metal 54 and contact 56. IC die 52 is connected to contact 46 and to trace metal 54 by wire bonding, for example, and contact 44 and contact 56 are connected respectively through plated holes 60, 62 to backside ground plane 41 and to I/O contact 42. Metal layer 50 supporting IC die 52 is also connected to the backside ground plane 41 by plated through vias 64, 66. In completing the module, the front side is covered by molding compound and the module is then mounted to another printed circuit board by soldering of backside ground 41 and I/O contact 42 to the second printed circuit board. A solder mask 68 is provided to prevent shorting of I/O contact 42 and the ground plane.--